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April 2015

FDB110N15A

N-Channel PowerTrench[®] MOSFET 150 V, 92 A, 11 m Ω

Features

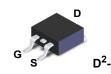
- $R_{DS(on)}$ = 9.25 m Ω (Typ.) @ V_{GS} = 10 V, I_D = 92 A
- · Fast Switching Speed
- · Low Gate Charge
- High Performance Trench Technology for Extremely Low $R_{DS(on)}$
- · High Power and Current Handling Capability
- RoHS Compliant

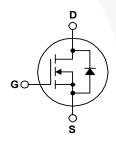
Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advance PowerTrench® process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Applications

- · Synchronous Rectification for ATX / Server / Telecom PSU
- · Battery Protection Circuit
- · Motor drives and Uninterruptible Power Supplies
- · Micro Solar Inverter





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol		Parameter	FDB110N15A	Unit
V _{DSS}	Drain to Source Voltage		150	V
V	Cata to Course Voltage	- DC	±20	V
V_{GSS}	Gate to Source Voltage	- AC (f > 1 Hz)	±30	V
I _D	Drain Current	- Continuous (T _C = 25°C)	92	А
	Drain Current	- Continuous (T _C = 100°C)	65	_ A
I _{DM}	Drain Current	- Pulsed (Note 1)	369	Α
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	365	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	6	V/ns
D	Davies Dissination	$(T_C = 25^{\circ}C)$	234	W
P_{D}	Power Dissipation	- Derate Above 25°C	1.56	W/°C
T _J , T _{STG}	Operating and Storage Temperat	-55 to +175	οС	
T _I	Maximum Lead Temperature for	Soldering, 1/8" from Case for 5 Seconds	300	οС

Thermal Characteristics

Syr	mbol	Parameter	FDB110N15A	Unit
$R_{\theta JC}$		Thermal Resistance, Junction to Case, Max.	0.64	°C/W
R_{\thetaJA}		Thermal Resistance, Junction to Ambient, Max.	62.5	10/00

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FDB110N15A	FDB110N15A	D ² -PAK	Tape and Reel	330 mm	24 mm	800 units

Electrical Characteristics $T_C = 25^{\circ}C$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	cteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150	-	-	V
ΔBV _{DSS} / ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, Referenced to 25°C	-	0.09	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V	-	-	1	μА
	Zero Gate voltage Drain Current	$V_{DS} = 120 \text{ V}, T_{C} = 150^{\circ}\text{C}$	-	-	500	
I _{GSS}	Gate to Body Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V	-	-	±100	nA

On Characteristics

V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$	2.0	-	4.0	٧
R _{DS(on)}	Static Drain to Source On Resistance	V _{GS} = 10 V, I _D = 92 A	-	9.25	11.0	mΩ
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 92 A	-	118	-	S

Dynamic Characteristics

C _{iss}	Input Capacitance	V - 75 V V - 0 V	-	3390	4510	pF
Coss	Output Capacitance	$V_{DS} = 75 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1 MHz	-	334	445	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 1/11/12	-\	14	-	pF
C _{oss} (er)	Engry Releted Output Capacitance	V _{DS} = 75 V, I _D = 92 A	-	583	-	pF
Q _{g(tot)}	Total Gate Charge at 10V		- \	47	61	nC
Q_{gs}	Gate to Source Gate Charge	$V_{GS} = 10 \text{ V}, V_{DS} = 75 \text{ V},$	-	16	-	nC
Q _{gs2}	Gate Charge Threshold to Plateau	I _D = 92 A	-	7.9	-	nC
Q_{gd}	Gate to Drain "Miller" Charge	(Note	4) -	9.7	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time			- /	25	60	ns
t _r	Turn-On Rise Time	$V_{DD} = 75 \text{ V}, I_{D} = 92 \text{ A},$		- /	26	62	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{G} = 4.7 Ω		-/	46	102	ns
t _f	Turn-Off Fall Time		(Note 4)	-	14	38	ns
ESR	Equivalent Series Resistance (G-S)	f = 1 MHz		/ -	2.5	-	Ω

Drain-Source Diode Characteristics

Is	Maximum Continuous Drain to Source Diode	Maximum Continuous Drain to Source Diode Forward Current			92	Α
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current			-	369	Α
V_{SD}	Drain to Source Diode Forward Voltage V _{GS} = 0 V, I _{SD} = 92 A		-	-	1.25	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 92 A, V _{DD} = 75 V,	-	89	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	255	-	nC

Notes:

- 1. Repetitive rating: pulse width-limited by maximum junction temperature.
- 2. L = 3 mH, I_{AS} = 15.6 A, R_G = 25 Ω , starting T_J = 25°C.
- 3. $I_{SD} \le 92$ A, di/dt ≤ 200 A/ μ s, $V_{DD} \le BV_{DSS}$, starting $T_J = 25^{\circ}C$.
- Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

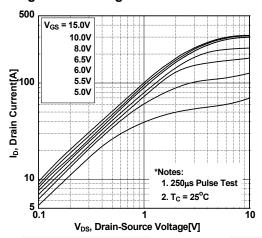


Figure 3. On-Resistance Variation vs.

Drain Current and Gate Voltage

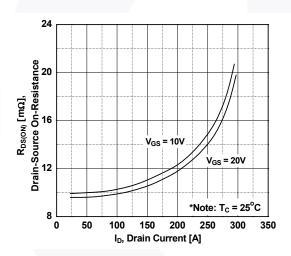


Figure 5. Capacitance Characteristics

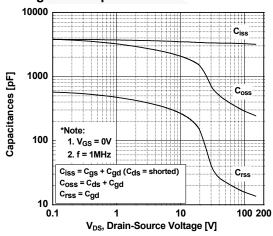


Figure 2. Transfer Characteristics

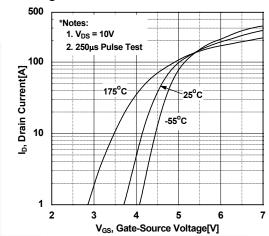


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

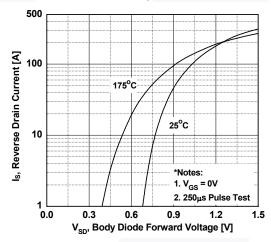
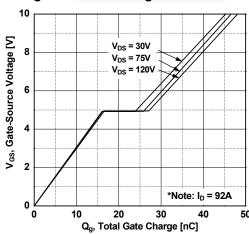


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

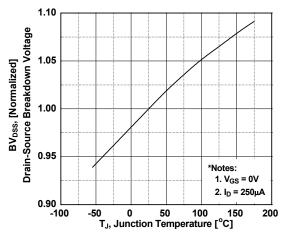


Figure 9. Maximum Safe Operating Area

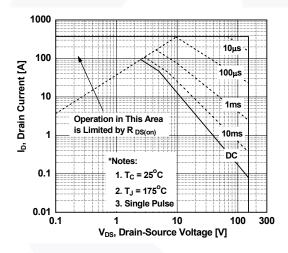


Figure 11. Eoss vs. Drain to Source Voltage

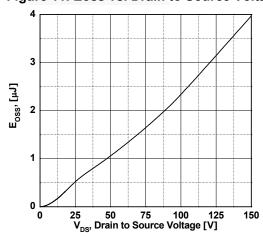


Figure 8. On-Resistance Variation vs. Temperature

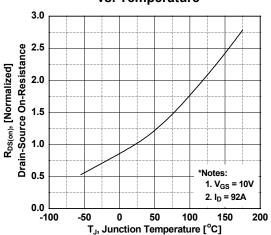
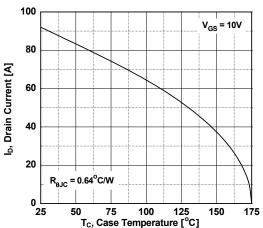
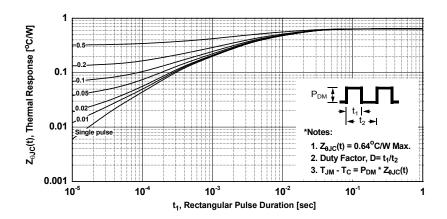


Figure 10. Maximum Drain Current vs. Case Temperature



Typical Performance Characteristics (Continued)

Figure 12. Transient Thermal Response Curve



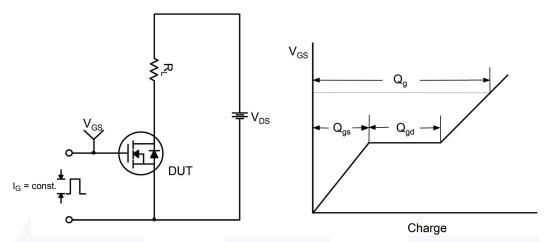


Figure 13. Gate Charge Test Circuit & Waveform

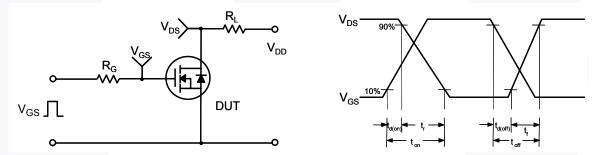


Figure 14. Resistive Switching Test Circuit & Waveforms

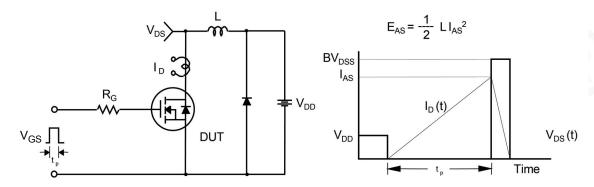


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

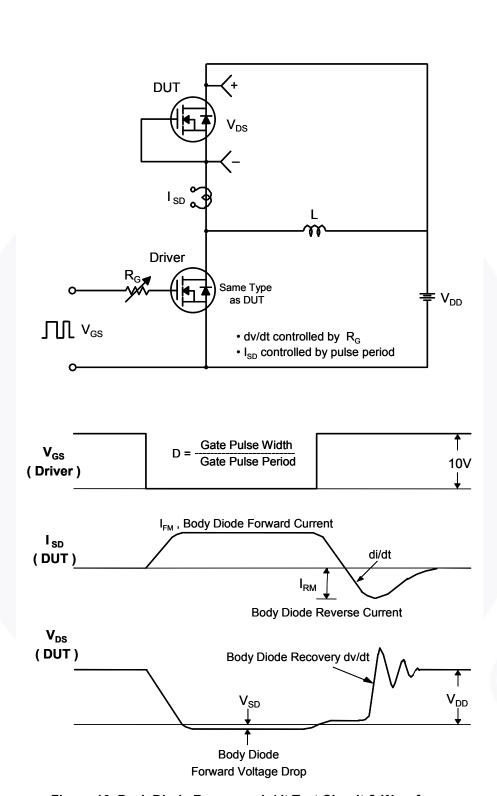
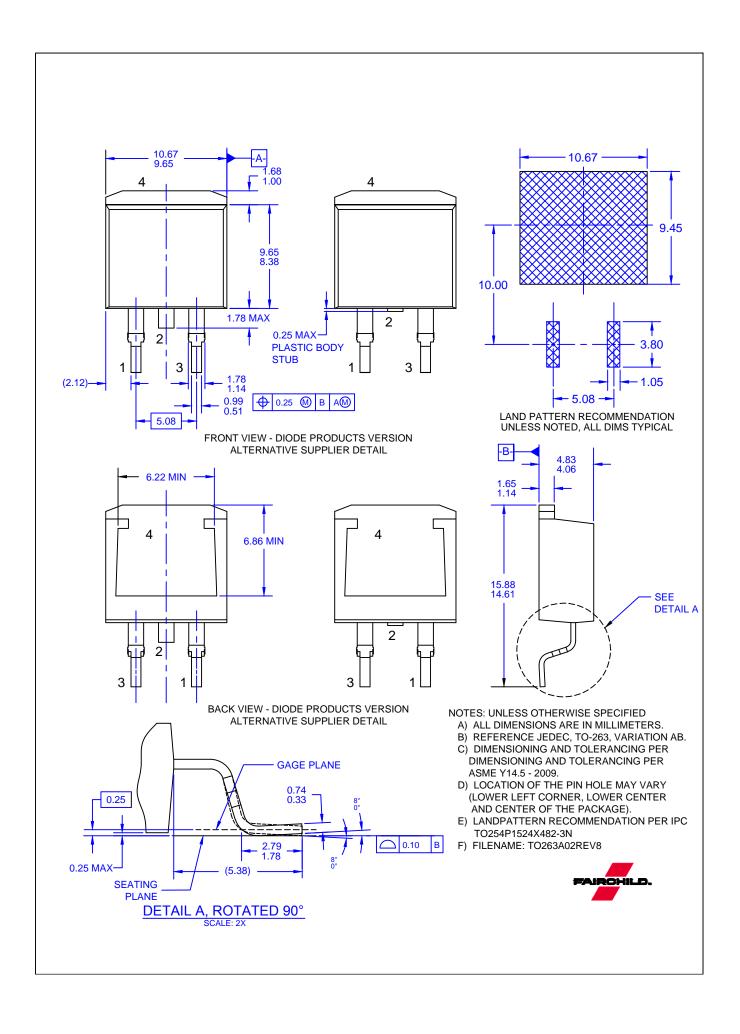


Figure 16. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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